TOSHIBA Field-Effect Transistor Silicon N-Channel MOS Type

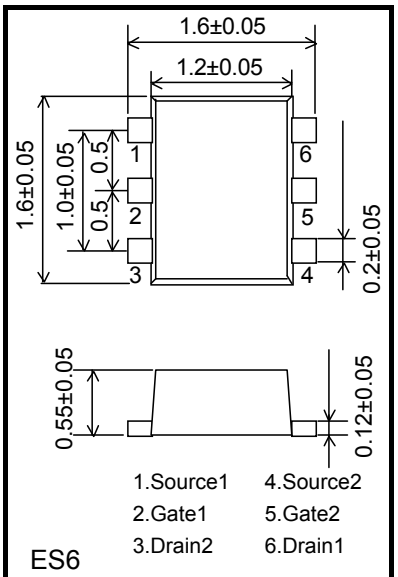
SSM6N37FE

○ High-Speed Switching Applications

○ Analog Switching Applications

- 1.5-V drive
- Suitable for high-density mounting due to compact package
- Low ON-resistance $R_{DS(ON)}$ = 5.60 Ω (max) (@V_{GS} = 1.5 V)
  $R_{DS(ON)}$ = 4.05 Ω (max) (@V_{GS} = 1.8 V)
  $R_{DS(ON)}$ = 3.02 Ω (max) (@V_{GS} = 2.5 V)
  $R_{DS(ON)}$ = 2.20 Ω (max) (@V_{GS} = 4.5 V)

単位: mm



JEDEC	—
JEITA	—
TOSHIBA	2-2N1D

Weight: 3.0 mg (typ.)

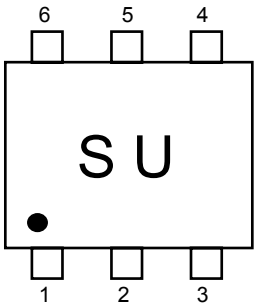
Absolute Maximum Ratings (Ta = 25°C) (Q1, Q2 Common)

Characteristic		Symbol	Rating	Unit
Drain–source voltage		V_{DSS}	20	V
Gate–source voltage		V_{GSS}	± 10	V
Drain current	DC	I_D	250	mA
	Pulse	I_{DP}	500	
Drain power dissipation		P_D (Note 1)	150	mW
Channel temperature		T_{ch}	150	°C
Storage temperature		T_{stg}	−55 to 150	°C

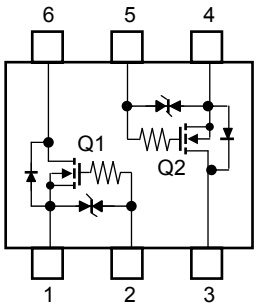
Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.
Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook (“Handling Precautions”/“Derating Concept and Methods”) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Total rating
Mounted on an FR4 board
(25.4 mm × 25.4 mm × 1.6 mm, Cu Pad: 0.135 mm^2 × 6)

Marking



Equivalent Circuit (top view)



Start of commercial production
2009-12

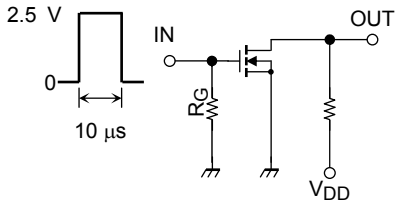
Electrical Characteristics (Ta = 25°C) (Q1, Q2 Common)

Characteristic		Symbol	Test Condition	Min	Typ.	Max	Unit
Drain-source breakdown voltage		$V_{(BR)\ DSS}$	I_D = 1 mA, V_{GS} = 0 V	20	—	—	V
		$V_{(BR)\ DSX}$	I_D = 1 mA, V_{GS} = -10 V	12	—	—	
Drain cutoff current		I_{DSS}	V_{DS} = 20 V, V_{GS} = 0 V	—	—	1	μA
Gate leakage current		I_{GSS}	V_{GS} = ±10 V, V_{DS} = 0 V	—	—	±1	μA
Gate threshold voltage		V_{th}	V_{DS} = 3 V, I_D = 1 mA	0.35	—	1.0	V
Forward transfer admittance		$\|Y_{fs}\|$	V_{DS} = 3 V, I_D = 100 mA (Note 2)	0.14	0.28	—	S
Drain-source ON-resistance		$R_{DS\ (ON)}$	I_D = 100 mA, V_{GS} = 4.5 V (Note 2)	—	1.65	2.20	Ω
			I_D = 50 mA, V_{GS} = 2.5 V (Note 2)	—	2.16	3.02	
			I_D = 20 mA, V_{GS} = 1.8 V (Note 2)	—	2.66	4.05	
			I_D = 10 mA, V_{GS} = 1.5 V (Note 2)	—	3.07	5.60	
Input capacitance		C_{iss}	V_{DS} = 10 V, V_{GS} = 0 V, f = 1 MHz	—	12	—	pF
Output capacitance		C_{oss}		—	5.5	—	
Reverse transfer capacitance		C_{rss}		—	4.1	—	
Switching time	Turn-on time	t_{on}	V_{DD} = 10 V, I_D = 100 mA	—	18	—	ns
	Turn-off time	t_{off}	V_{GS} = 0 to 2.5 V, R_G = 50 Ω	—	36	—	
Drain-source forward voltage		V_{DSF}	I_D = -250 mA, V_{GS} = 0 V (Note 2)	—	-0.9	-1.2	V

Note 2: Pulse test

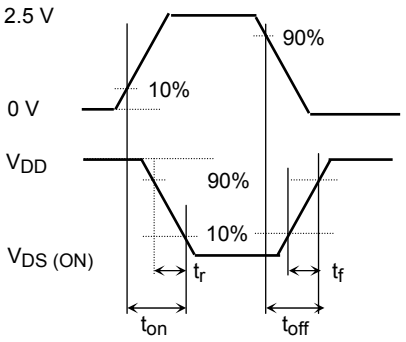
Switching Time Test Circuit (Q1, Q2 Common)

(a) Test Circuit



V_{DD} = 10 V
R_G = 50 Ω
Duty ≤ 1%
V_{IN}: t_r, t_f < 5 ns
Common Source
Ta = 25°C

(b) V_{IN} and (c) V_{OUT}



Precaution

Let V_{th} be the voltage applied between gate and source that causes the drain current (I_D) to be low (1mA for the SSM6N37FE). Then, for normal switching operation, $V_{GS(on)}$ must be higher than V_{th}, and $V_{GS(off)}$ must be lower than V_{th}. This relationship can be expressed as: $V_{GS(off)} < V_{th} < V_{GS(on)}$.

Take this into consideration when using the device.

Do not use this device under avalanche mode. It may cause the device to break down.

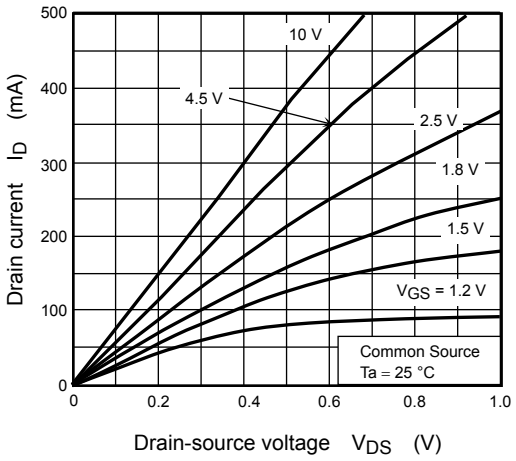
Handling Precaution

When handling individual devices that are not yet mounted on a circuit board, make sure that the environment is protected against electrostatic discharge. Operators should wear antistatic clothing, and containers and other objects that come into direct contact with devices should be made of antistatic materials.

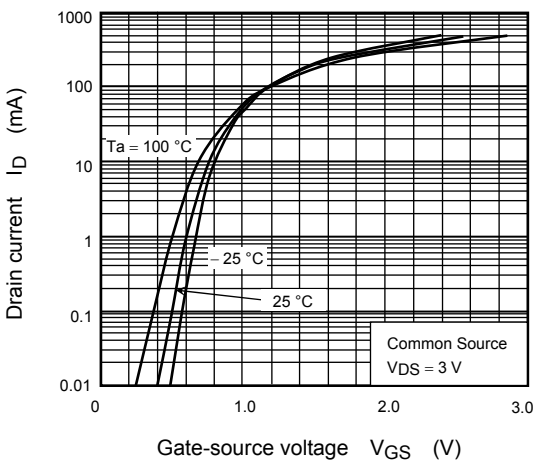
Thermal resistance $R_{th(j\text{-}a)}$ and drain power dissipation P_D vary depending on board material, board area, board thickness and pad area. When using this device, please take heat dissipation into consideration.

(Q1, Q2 Common)

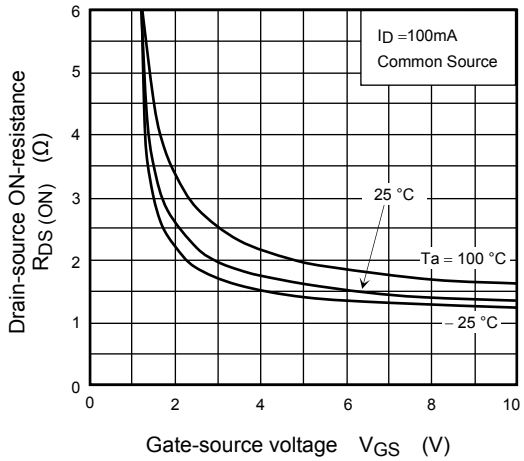
$I_D - V_{DS}$



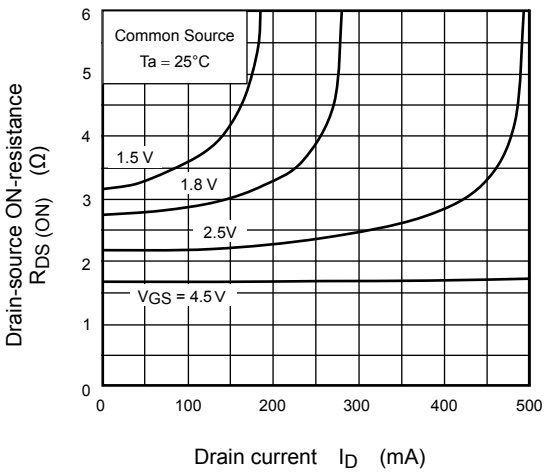
$I_D - V_{GS}$



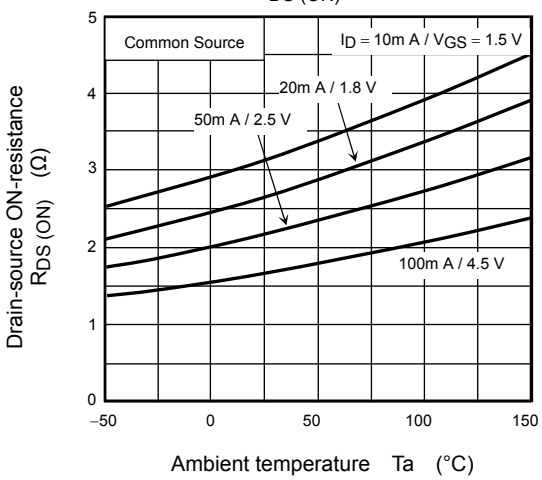
$R_{DS\ (ON)} - V_{GS}$



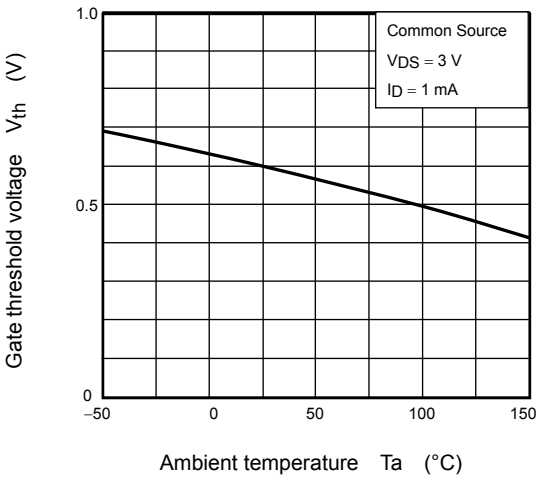
$R_{DS\ (ON)} - I_D$



$R_{DS\ (ON)} - Ta$

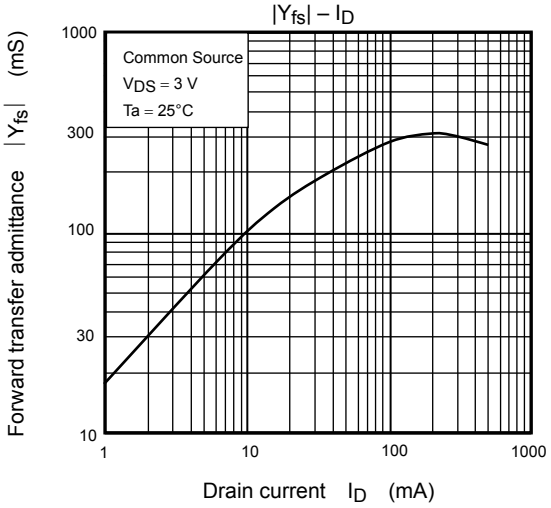


$V_{th} - Ta$

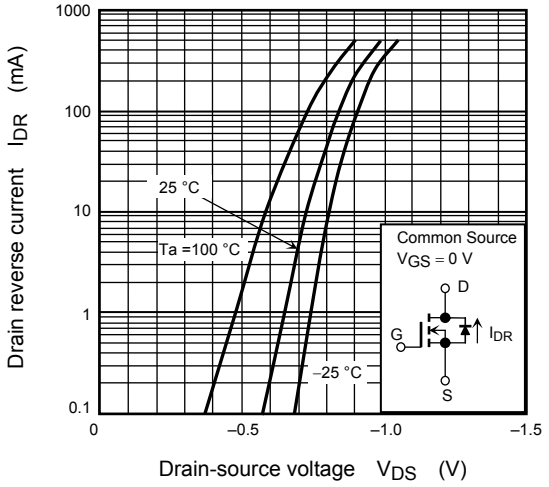


(Q1, Q2 Common)

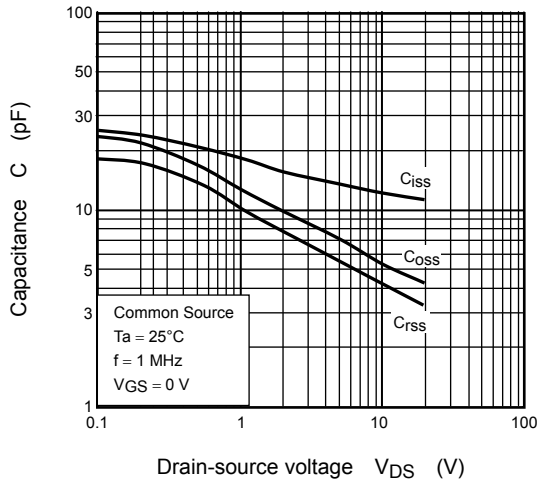
$|Y_{fs}| - I_D$



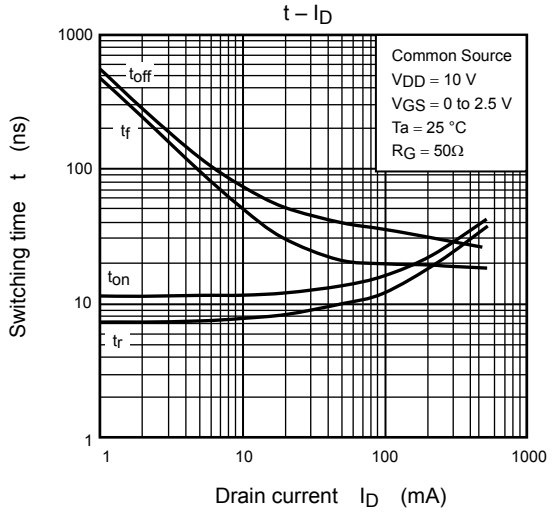
$I_{DR} - V_{DS}$



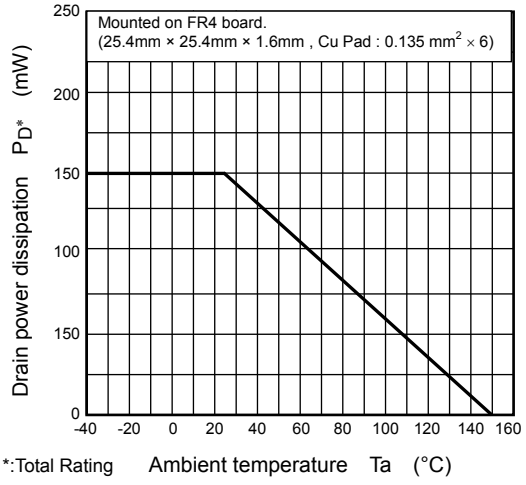
$C - V_{DS}$



$t - I_D$



$P_D^* - T_a$



*:Total Rating

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